# NPN Silicon Power Darlington Transistors

The MJE5740 and MJE5742 Darlington transistors are designed for high-voltage power switching in inductive circuits.

#### **Features**

• These Devices are Pb-Free and are RoHS Compliant\*

### **Applications**

- Small Engine Ignition
- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage MJE5740 MJE5742	V <sub>CEO(sus)</sub>	300 400	Vdc
Collector–Emitter Voltage MJE5740 MJE5742	V <sub>CEV</sub>	600 800	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	8	Vdc
Collector Current – Continuous – Peak (Note 1)	I <sub>C</sub> I <sub>CM</sub>	8 16	Adc
Base Current – Continuous – Peak (Note 1)	I <sub>B</sub> I <sub>BM</sub>	2.5 5	Adc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	2 0.016	W W/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	100 0.8	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

#### THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	1.25	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	TL	275	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

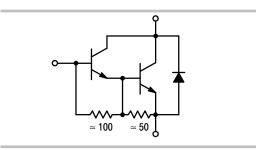
\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

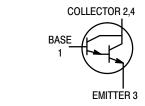


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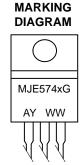
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POWER DARLINGTON TRANSISTORS 8 AMPERES 300-400 VOLTS 80 WATTS









#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS (Note 2)		•			
	· CEO(SuS)	300 400	_ _	_ _	Vdc
Collector Cutoff Current (V <sub>CEV</sub> = Rated Value, V <sub>BE(off)</sub> = 1.5 Vdc) (V <sub>CEV</sub> = Rated Value, V <sub>BE(off)</sub> = 1.5 Vdc, T <sub>C</sub> = 100°C)	I <sub>CEV</sub>	_ _	_ _	1 5	mAdc
Emitter Cutoff Current (V <sub>EB</sub> = 8 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	_	_	75	mAdc
SECOND BREAKDOWN					
Second Breakdown Collector Current with Base Forward Biased	I <sub>S/b</sub>	See Figure 6			
Clamped Inductive SOA with Base Reverse Biased	RBSOA	See Figure 7			
ON CHARACTERISTICS (Note 2)					
DC Current Gain ( $I_C = 0.5$ Adc, $V_{CE} = 5$ Vdc) ( $I_C = 4$ Adc, $V_{CE} = 5$ Vdc)	h <sub>FE</sub>	50 200	100 400	- -	_
Collector–Emitter Saturation Voltage ( $I_C$ = 4 Adc, $I_B$ = 0.2 Adc) ( $I_C$ = 8 Adc, $I_B$ = 0.4 Adc) ( $I_C$ = 4 Adc, $I_B$ = 0.2 Adc, $I_C$ = 100°C)	V <sub>CE(sat)</sub>	- - -	- - -	2 3 2.2	Vdc
Base–Emitter Saturation Voltage ( $I_C$ = 4 Adc, $I_B$ = 0.2 Adc) ( $I_C$ = 8 Adc, $I_B$ = 0.4 Adc) ( $I_C$ = 4 Adc, $I_B$ = 0.2 Adc, $T_C$ = 100°C)	V <sub>BE(sat)</sub>	- - -	- - -	2.5 3.5 2.4	Vdc
Diode Forward Voltage (Note 3) (I <sub>F</sub> = 5 Adc)	V <sub>f</sub>	-	-	2.5	Vdc
SWITCHING CHARACTERISTICS		1	.1	ı	,

Typical Resistive Load (Table 1)						
Delay Time	$(V_{CC} = 250 \text{ Vdc}, I_{C(pk)} = 6 \text{ A}$ $I_{B1} = I_{B2} = 0.25 \text{ A}, t_p = 25 \mu s,$	t <sub>d</sub>	_	0.04	_	μs
Rise Time		t <sub>r</sub>	_	0.5	_	μs
Storage Time	$I_{B1} = I_{B2} = 0.25 \text{ A}, I_p = 25 \mu\text{s},$ Duty Cycle $\leq 1\%$ )	t <sub>s</sub>	_	8	_	μs
Fall Time		t <sub>f</sub>	-	2	-	μs
Inductive Load, Clamped (Table 1)						
Voltage Storage Time	(I <sub>C(pk)</sub> = 6 A, V <sub>CE(pk)</sub> = 250 Vdc	t <sub>sv</sub>	_	4	_	μs
Crossover Time	$(I_{C(pk)} = 6 \text{ A}, V_{CE(pk)} = 250 \text{ Vdc}$ $I_{B1} = 0.06 \text{ A}, V_{BE(off)} = 5 \text{ Vdc})$	t <sub>c</sub>	_	2	-	μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **ORDERING INFORMATION**

Device	Package	Shipping
MJE5740G	TO-220 (Pb-Free)	5011-11- / D-11
MJE5742G	TO-220 (Pb-Free)	50 Units / Rail

<sup>2.</sup> Pulse Test: Pulse Width 300 μs, Duty Cycle = 2%.

<sup>3.</sup> The internal Collector–to–Emitter diode can eliminate the need for an external diode to clamp inductive loads. Tests have shown that the Forward Recovery Voltage (V<sub>f</sub>) of this diode is comparable to that of typical fast recovery rectifiers.

## **TYPICAL CHARACTERISTICS**

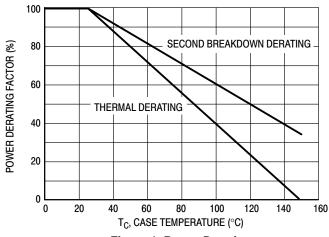


Figure 1. Power Derating

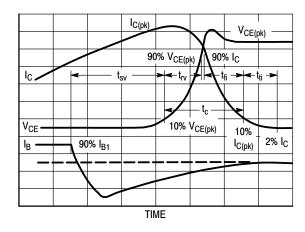


Figure 2. Inductive Switching Measurements

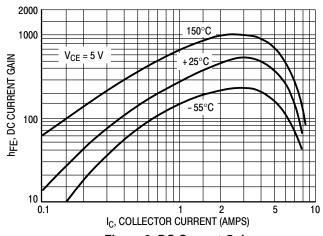


Figure 3. DC Current Gain

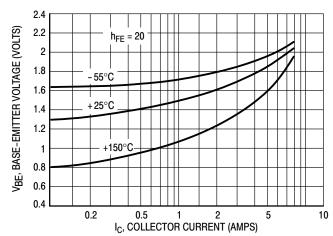


Figure 4. Base-Emitter Voltage

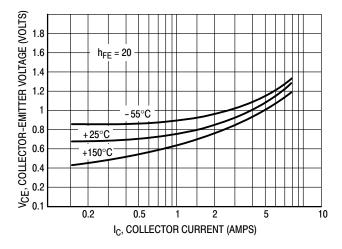
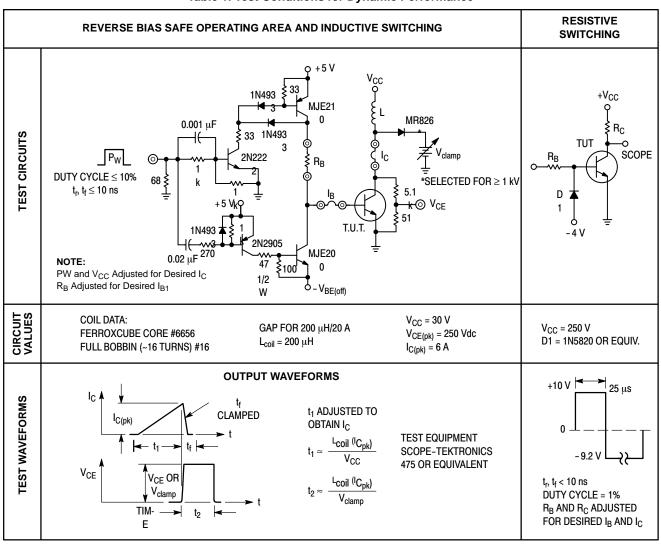


Figure 5. Collector-Emitter Saturation Voltage

**Table 1. Test Conditions for Dynamic Performance** 



#### SAFE OPERATING AREA INFORMATION

### **FORWARD BIAS**

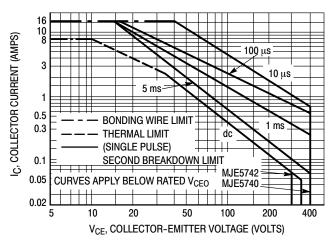
There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on  $T_C = 25^{\circ}C$ ;  $T_{J(pk)}$  is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when  $T_C \ge 25^{\circ}C$ . Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 6 may be found at any case temperature by using the appropriate curve on Figure 1.

#### **REVERSE BIAS**

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turnoff. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 7 gives the complete RBSOA characteristics.

The Safe Operating Area figures shown in Figures 6 and 7 are specified ratings for these devices under the test conditions shown.



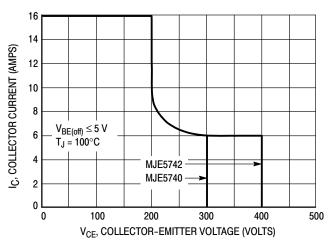
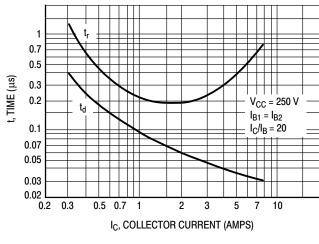


Figure 6. Forward Bias Safe Operating Area

Figure 7. Reverse Bias Safe Operating Area

## **RESISTIVE SWITCHING PERFORMANCE**





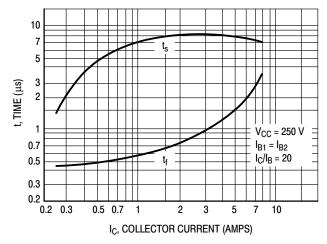
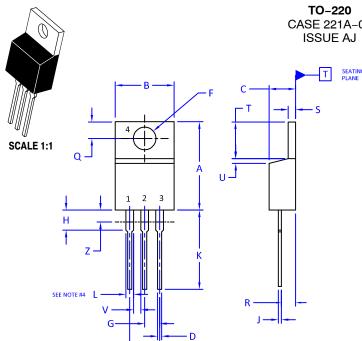


Figure 9. Turn-Off Time

## **MECHANICAL CASE OUTLINE**



CASE 221A-09

**DATE 05 NOV 2019** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

#### 4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMI	ETERS
DIM	MIN.	MAX.	MIN.	MAX.
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11	:	STYLE 12	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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